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Tsi310[™] Evaluation Board User Manual

80B6020_MA002_03

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Tsi310 Evaluation Board User Manual

This document describes how to test the key features of the Tsi310 using the Tsi310 Evaluation board. The following topics are discussed:

- "Features" on page 4
- "Description" on page 4
- "Jumper Settings" on page 5
- "Switch Settings" on page 9
- "Schematic Diagrams" on page 9
- "Unsupported Functions" on page 20

Revision History

80B6020_MA002_03, September 2009

This document was rebranded as IDT. It does not include any technical changes.

80B6020_MA002_02, June 2004

This document supports the following:

- Board part number Tsi310A-RDK1 v1.0; device part number Tsi310A-133CE
- Board part number Tsi310-RDK1 v1.0; device part number Tsi310-133CE

Please note that there are no technical differences between this document and the previous version of the evaluation board manual, document number 80B6020_MA002_01.

80B6020_MA002_01, February 2004

This document supports part numbers, Tsi310-133CE and Tsi310A-133CE. Please note that there are no technical differences between this document and the previous version of the evaluation board manual, document number 80B6000_MA002_02.

1. Features

The Tsi310 Evaluation board has the following features:

- Primary interface plugs into any standard 3.3V PCI option card slot
- Provides one secondary 3.3V PCI-X slot with operation up to 133.33 MHz, with optional unpopulated slot
- Interconnect complies with the specifications:
 - PCI Local Bus Specification (Revision 2.2)
 - PCI-X Addendum to PCI Local Bus Specification (Revision 1.0a)
 - *PCI-to-PCI Bridge Architecture Specification (Revision 1.1)*

2. Description

The Tsi310 Evaluation board is intended to operate in a "covers off" laboratory environment while installed in a host PC. The board consists of the following:

- One 64-bit PCI-X compatible card edge connector that connects to the primary side of the bridge device (see Figure 1)
- Two secondary 64-bit PCI-X compatible connectors available at the top of the evaluation board

For program debug and performance measurements, the evaluation board's extended height provides access to jumpers and facilitates the use of a logic analyzer interface card for analysis of the PCI bus activity.

Power for the evaluation board is provided from the 64-bit PCI-X-compatible card edge. Power for the Tsi310 device is provided by an on-board regulator that develops 2.5V from the host +5V supply. Power-on status of the board is reported by LED DS1 on the 2.5V regulator output.

The on-board clock rate selection is provided by user-activated switch settings. The jumpers permit experimentation with various PCI conventional and PCI-X modes.

3. Jumper Settings

The following table shows the jumper settings for the evaluation board. The location of the board's jumpers, switches, and other devices is illustrated in Figures 1 and 2.

Table	1:	Jum	ber	Settings
10010	•••	• • • • • •		oottingo

Device Number	Description
R118	Controls PCI-X capability (PCIXCAP) presented to the primary bus. This is a solder-in part that is unpopulated by default. No resistor: 133 PCI-X 10K resistor: 66 PCI-X 0-ohm resistor: PCI Conventional
R80, R81	Control PRST1# PRSNT2# identify the power dissipation of the add-in card to the host system. These resistors are configured for the maximum power requirement of 25 watts.
J3	Secondary driver mode override: The Tsi310 automatically selects driver impedance based on bus mode. ON: Selects multi-point (conventional PCI, PCI-X66, and PCI-X100), point-to-point (PCI-X133). Note: This jumper is installed by default. OFF: Selects point-to-point (conventional PCI, PCI-X66, and PCI-X100), multi-point (PCI-X133).
J4	 Primary driver mode control: The Tsi310 automatically selects driver impedance based on bus mode. ON: Selects multi-point (conventional PCI, PCI-X66, and PCI-X100), point-to-point (PCI-X133). Note: This jumper is installed by default. OFF: Selects point-to-point (conventional PCI, PCI-X66, and PCI-X100), multi-point (PCI-X133).
J5	Primary side M66EN pin: Has no function when the primary bus is operating in PCI-X mode. Populating this jumper grounds M66EN, thereby disabling 66 MHz operation. Note: This jumper is not installed.
J6	Controls selection of secondary bus PCI-X maximum frequency. This jumper is only applicable when secondary bus is operating in PCI-X mode and PCIXCAP indicates 133 MHz bus speed. When J6 is jumpered, the S_SEL100 signal is low indicating 133 MHz operation; otherwise, 100 MHz operation is selected. Users must ensure the selection of J6 matches S1-2 and S1-3 (clock frequency control) settings as described in Section 4 on page 9. Note: This jumper is installed by default.
J7	Internal arbitration enabled signal: Tests the capability of permitting external arbitration on the secondary bus by disabling the internal arbiter. An external arbiter chip is required when jumper is removed. Note: This jumper is installed by default, which means the arbiter is enabled.

Table 1: Jumper Settings (Continued)

Device Number	Description
J8	Pins 1 and 2 jumpered forces the secondary bus to PCI-X 66. Pins 2 and 3 jumpered forces the secondary bus into PCI conventional mode. Note: This jumper is installed in positions 2 and 3 by default.
Jð	JTAG test interface for the Tsi310: The JTAG mechanical form factor is not standardized. This connector is normally not installed.
J10	Power consumption test interface for the Tsi310. Note: This jumper is not installed.

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4. Switch Settings

The functions and settings of the switches are described in Tables 2 and 3; the location of the switches is displayed in Figure 1 on page 7.

Switch S1 Element ^a	Default Setting ^b	Function
S1-1	off	Provides output enable for the C9531 clock generator.
S1-2, S1-3	on	Controls clock frequency generated by U5 (see Table 3) for the PCI-X Bridge secondary bus.
S1-4	off	Operates the spread-spectrum clock controls available from the C9531. The I_2C interface to the C9531 is not wired, which results in a 0.5% downspread (-0.5%, +0.0) of the generator clock output when spread-spectrum is selected. Default setting disables spread-spectrum operation.
S1-5 through S1-8	off	Not used.

Table 2: Switch S1 Functions and Default Settings

a. The DIP switch on the evaluation board has a silk-screen label of "S1". The notation used in the tables for the DIP switch is S1-x, where "S1" is the silk-screen reference locator, and "x" is the switch location on the DIP switch.

b. closed = on; open = off

Table 3: Secondary Clock Speed Generation Selection

lumper/	Signal	PCI Mode		PCI-X Mode		
Switch #	Name	33 MHz ^a	66 MHz	66 MHz	100 MHz	133 MHz
Sw1-3	C9531AT Pin S0	0 (closed)	1 (open)	1 (open)	0 (closed)	1 (open)
Sw1-2	C9531AT Pin S1	0 (closed)	0 (closed)	0 (closed)	1 (open)	1 (open)
J6	S_SEL100	don't care	don't care	don't care	not installed	installed
J8	PCIXCAP	2-3	2-3	1-2	not installed	not installed

a. The Tsi310 Evaluation board is shipped with this default configuration.

5. Schematic Diagrams

This section illustrates the schematic diagrams for the Tsi310 Evaluation board.

Figure 3: Schematic Diagram — Page 1 υ 33F8029 N 1167 JUMP FOR FOR 33 MHZ DO_NOT_POPULATE BERG2X NO RES 10K OHM RES ZERO OHM RES ЦŅ 118K 2 PRI_M66 ĝ PCIX-133 PCIX-66 PCI CONU IAE PRI_XCAP 10 E ₿ 7560: 1560 7550: 1560 7550: 1560 7550: 1560 1756: 2756 1756: 27550 1756: 27560 1756: 27550 1756: 27560 17560 1756: 27560 1756: 27560 17560 ::1750:2750 ::1758:2758 ::1750:2750 :: 750: 1500 1A54



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Figure 4: Schematic Diagram — Page 2



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m Œ υ DATE: 5-01-2003 3 OF 10 100NF_6.3U C44 100NF_6.3U C46 100NF_6. 3U C43 -mn ⊣ຕທ PAGE: LOW Mo 100NF_6.3U C61 100NF_6. 3U CS0 100NF_6.3U C47 I 280 3.30 BRIDGE SEMICONDUCTOR Low 100NF_6.3U C54 133 PCI-X 100NF_6. 3U C141 100NF_6. 3U C64 . СAР ЧH n P Low TUNDRA LOW TUNDRA 100NF_6. 3V C144 100NF_6. 3U C140 100NF_6.3U C139 -າເທທະ - տտե ЧU ++• ENGINEER: LOW ð TITLE: 0-UM4IND2000 221 100NF_6.3U C150 -mn E E MO tso HEE 1330 NEE 1501 100NF_6.3V CI55 -000 NEE 1231 133 PCI-X B IC 304HPBGA U14 4 Ø90 Pasi aau 4 OF 548 530 330 LIZINE_6. 3U CI53 0.40084 TRST PMRSENSE Ϋ́́ DO_NOT_POPULATE J9 PS-16DS-WXA RWPPC4XX đ 100NF_6. 3U CI52 REG_2.5U 33F8029 1248 EHOLEII I77 BERC AEHOLE Ê ¥¥ A 6 ĝ 13.30 DØ3 WV-s 823 133 PCI-X BRIDGE IC U14 304HPBGA 1D0 XCLK_OUT 4 JTG_-3 OF T_MODECTL T_RI# ۲<u>۲</u> TEST_CE0 JTG_TCK JTG_TDI JTG_TMS JTG_TRST T_DI1# T_DI2# P_UDDA S_VDDA ŶĿ TUNDRA W. CØ1 W22 Y21 AAØ4 A21 3B21 C22 C22 C23 723 ¥∰ ® ź\$∐• CIE8 BLM31A700S_R RES_PU<8..6> 1508 330 330 ¥ BLM31A7005_R R115 MILS 5773 RETI SET I 8 Ê FURITE OUP 80 NN REG_2.5U 10 ŝ ERRITE C39 1252 Laszi asei i ₩Y ŝ ENSI ENSI ы. Э. Э. υ ш Œ

Figure 5: Schematic Diagram — Page 3

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Figure 6: Schematic Diagram — Page 4



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П m 5-01-2003 10 I235 3.30 5 P DATE: ü 100NF_6.3U C77 100NF_6.3U C76 TUNDRA 133 PCI-X BRIDGE 100NF_6.3U C75 M2:::Ø. IN M2:::.8. IN S_CLK2 B_CLK2 M2:::8. IN M2:::8. IN S_CLK3 S_CLK3 100NF_6.3U C70 S_CLK1 SEMICON DRA -_6.30 100NF_6.3U C65 C142 80P 100NF_ 1000 ENGINEEF Ë 31.92 11.31 SOIC RS2 UCC=+3.3U U13 74LCX125M 100NF_6, 3U C55 100NF_6. 3U C63 de la C30 2222 B42 ITSY 5 3 1221 +3.3V -9<u>9708</u>70 100NF_6. 3U C42 -6.30 I219 UDD2 100NF. CS2 C9531AT 13 12 50 BLM31A7005_R ETI NEE P65 IA<2-0> INTERNALLY PULLED UP 80000 0000 0000 100NF_6, 3U C41 100NF_6. 3U C45 a⊢n éččč C9531AT T550P28_1 1215 U10 2611 2 M 15 1 R44 S ð C34 8 88 531 1 EHOLEA EHOLEA I 220 EHOLEA DO_NOT_POPULATE_ - 8 CB3LV-3C-33. 3330-T 6 8 8 1 31.602 R53 1214 RES_PU<8..6> HOLE1. U6 I164 77F9110 1218 +3.3v 8 - LU ŗ E4 I173 EHOLE11 EHOLE11 8. 1U C29 ЦNЯ BHITCHB 10X \$£1 I21 181 10 U6 37F91: SOIC 83 E3 EHOLE11 I172 EHOLEA ≶₿ t SH si he 1217 +3.5v DEFAULT SETTINGS SYSCLK = ENABLE SPECTRUM OE = OPEN = 1 SI = OPEN = 1 SSC = OPEN = 1 SSCG = OPEN = 1 S_REQ_PU<6..3> EHOLE11 1175 FHOLE11 SSCG = Ø = SPREAD 5 ₿ 8 -0-NOTES: 2AB H . ບັດທີ່ທີ່ 4 ເກີເລີ້ - ຜູ້ ٧Ŷ

Figure 7: Schematic Diagram — Page 5

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Figure 8: Schematic Diagram — Page 6



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Figure 9: Schematic Diagram — Page 7



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Figure 10: Schematic Diagram — Page 8

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Figure 11: Schematic Diagram — Page 9

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Figure 12: Schematic Diagram — Page 10

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6. Unsupported Functions

The following table describes functions that are not supported by the Tsi310 Evaluation board.

Table 4: Unsupported Functions and Pi	ns
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Function	Connector Location	Comments
Power management support (PME)	Pin A19, edge card	Reserved and not wired.
Standby power (3.3VAUX)	Pin A14, edge card	Not connected to a standby power source.
-5VOLTS	-	Available from ATX power supply at ehole U20. Not required by PCI interface.
PRSNT1#, PRSNT2#	-	PRSNT1# is tied low by R80 at the edge card connector so the evaluation board is recognized as occupying a host slot in compliance with the PCI specification.
Hot plug	-	The evaluation board does not support hot plugging.

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